描述 / Descriptions

SOT23-6 塑料封装 P 沟道 MOS 管。
P-channel MOSFET in a SOT23-6 Plastic Package。

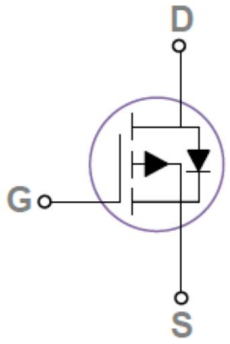
特征 / Features

V_{DS}(V)=-30V
I_D=-4.2A(V_{GS}=-10V)
RDS(ON)<50mΩ(VGS=-10V)
RDS(ON)<65mΩ(VGS=-4.5V)

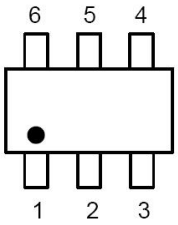
用途 / Applications

适用于作负载开关或脉宽调制应用。
This device is suitable for use as a load switch or in PWM applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1：D　PIN 2：D　PIN 3：G　PIN 4： S　PIN 5：D　PIN 6：D

印章代码 / Marking

见印章说明。See Marking Instructions

极限参数 / Absolute Maximum Ratings(T_a=25℃)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DSS}	-30	V
Drain Current – Continuous	I_D(T_a=25℃)	-4.2	A
Drain Current- Continuous [A]	I_D(T_a=70℃)	-3.5	A
Pulsed Drain Current [B]	I_{DM}	-30	A
Gate-Source Voltage	V_{GS}	±12	V
Maximum Power Dissipation [A]	P_D(T_a=25℃)	1.4	W
Total Power Dissipation [A]	P_D(T_a=70℃)	1.0	W
Maximum Junction-to-Ambient(Note 1)	$R_{\theta JA}$	125	℃/ W
Maximum Junction-to-Lead [C]	$R_{\theta JL}$	60	℃/W
Junction and Storage Temperature Range	T_j, T_{stg}	-55 ~ 150	℃

电性能参数 / Electrical Characteristics(T_a=25℃)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V I_D=-250μA	-30			V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=-24V V_{GS}=0V T_j=25℃			-1	μA
		V_{DS}=- 24V V_{GS}=0V T_j=55℃			-5	μA
Gate-Source Leakage Current	I_{GSS}	V_{GS}=±12V V_{DS}=0V			±0.1	uA
On–State Drain Current	$I_{D(on)}$	V_{GS}=-4.5V V_{DS}=-5V	-25			A
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} I_D=-250μA	-1.0		-2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=-10V I_D=-4.2A		37	50	mΩ
	$R_{DS(on)}$	V_{GS}=-10V I_D=-4.2A T_J=125℃			75	
	$R_{DS(on)}$	V_{GS}=-4.5V I_D=-4A		58	65	
Forward Transconductance	g_{FS}	V_{DS}=-5V I_D=-5A	7	11		S
Drain–Source Diode Forward Voltage	V_{SD}	V_{GS}=0V I_S=-1A		-0.75	-1.0	V

电性能参数 / Electrical Characteristics(T_a=25℃)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Input Capacitance	C_{iss}	V_{DS}=-15V V_{GS}=0V f=1MHz		957		pF
Output Capacitance	C_{oss}			115		
Reverse Transfer Capacitance	C_{rss}			77		
Gate resistance	R_g	V_{GS}=0V V_{DS}=0V, f=1MHz		6		Ω
Total Gate Charge	Q_g	V_{GS}=-4.5V V_{DS}=-15V I_D=-4A		9.4		nC
Gate Source Charge	Q_{gs}			2		
Gate Drain Charge	Q_{gd}			3		
Turn–On Delay Time	$t_{d(on)}$	V_{GS}=-10V R_L=3.6Ω V_{DS}=-15V R_{GEN}=6Ω		6.3		ns
Turn–On Rise Time	t_r			3.2		
Turn–Off Delay Time	$t_{d(off)}$			38.2		
Turn–Off Fall Time	t_f			12		
Body Diode Reverse Recovery Time	t_{rr}	I_F=-4A, dI/dt=100A/μs		20.2		ns
Body Diode Reverse Recovery Charge	Q_{rr}	I_F=-4A, dI/dt=100A/μs		11.2		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

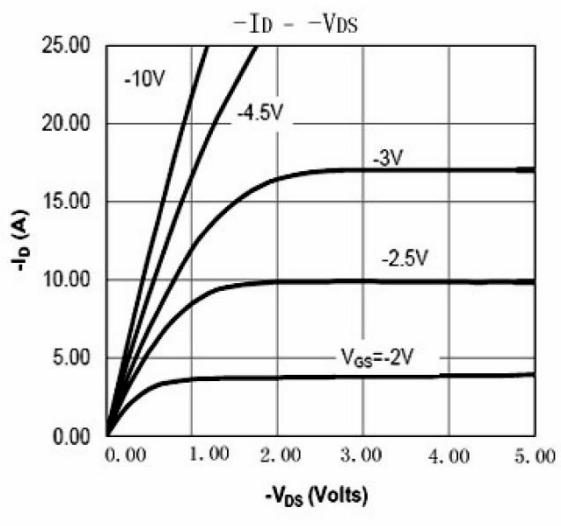
B: Repetitive rating, pulse width limited by junction temperature.

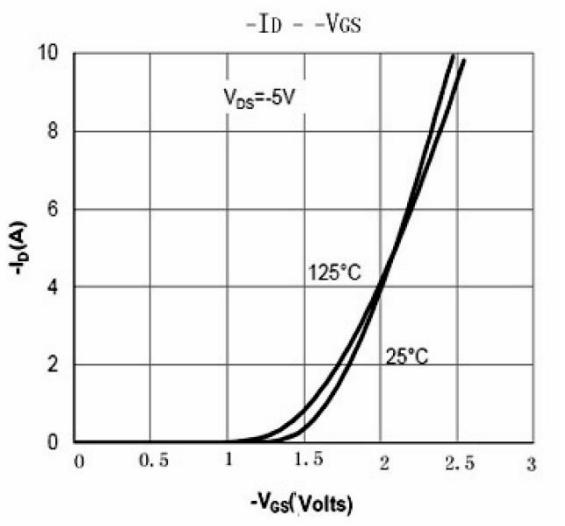
C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

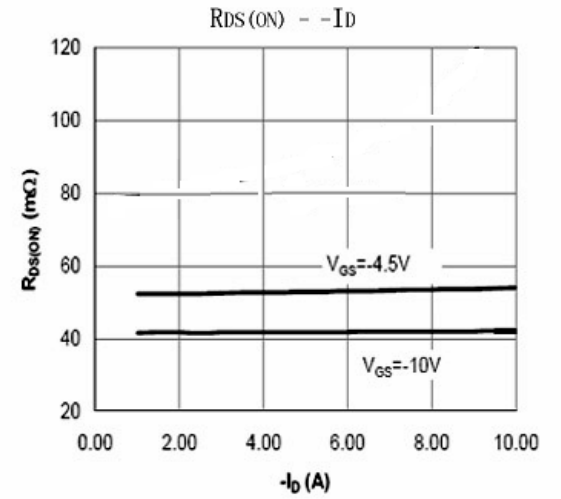
D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

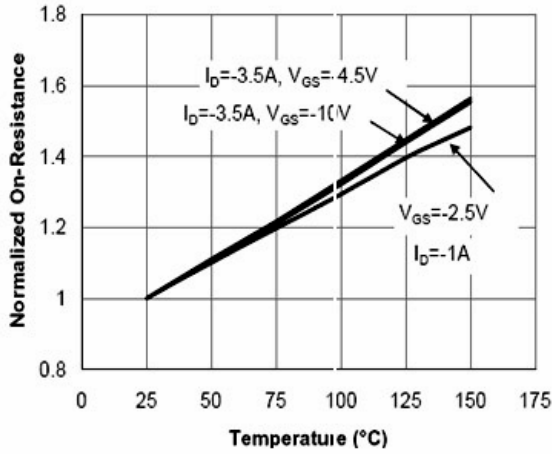
E. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

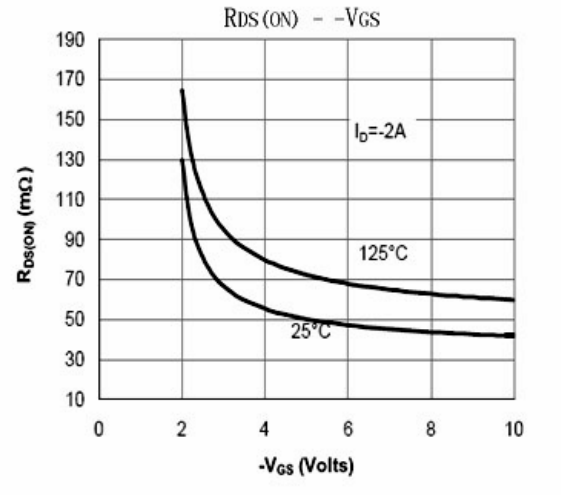
电参数曲线图 / Electrical Characteristic Curve

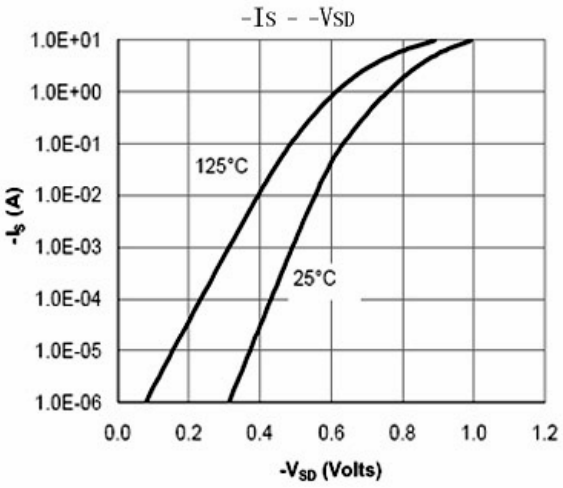




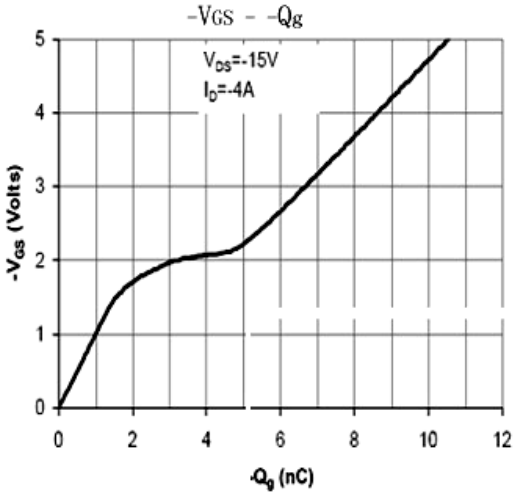


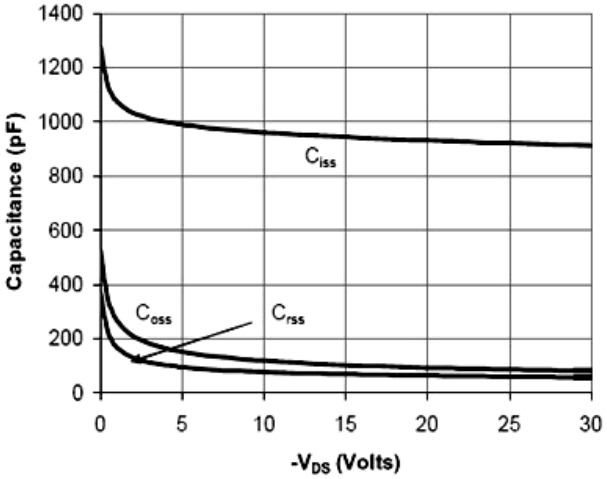




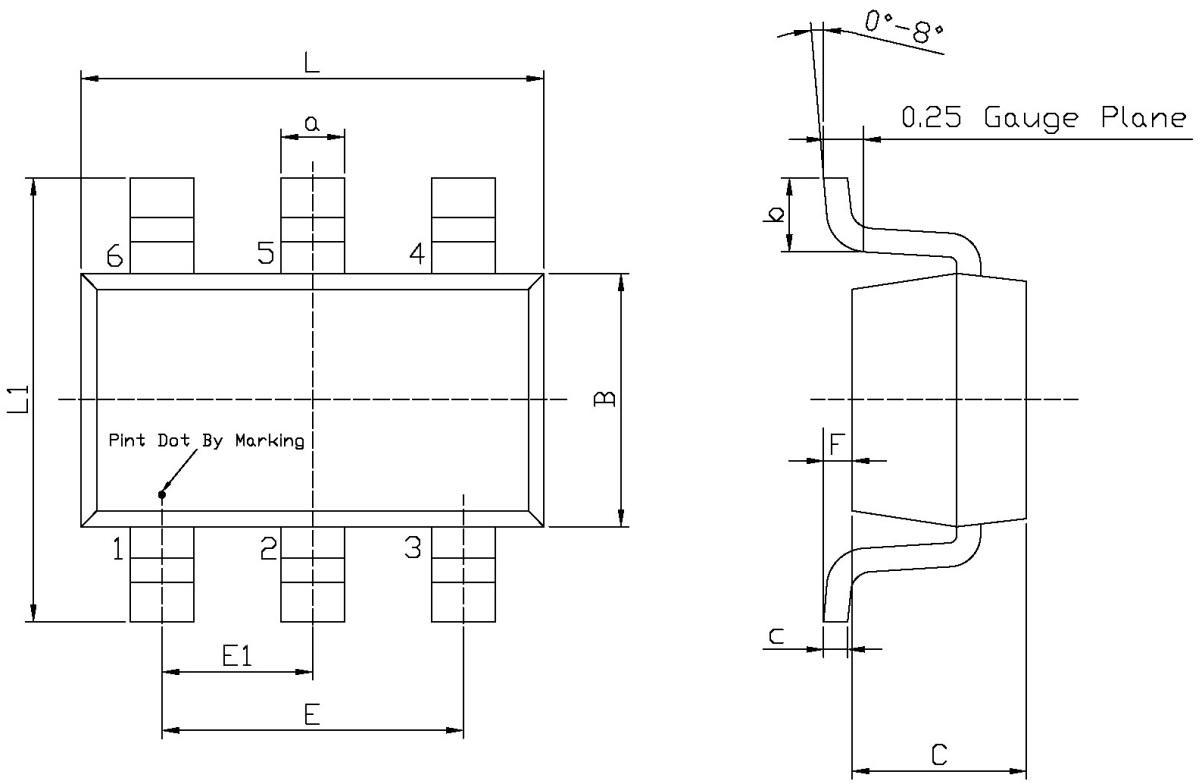


电参数曲线图 / Electrical Characteristic Curve





外形尺寸图 / Package Dimensions

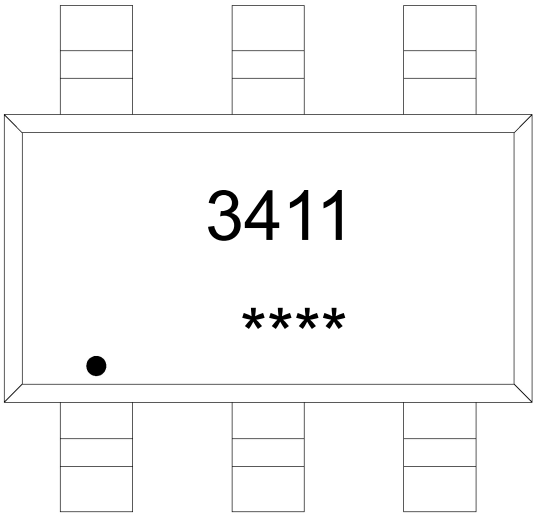


Unit: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.82	3.02	E1	0.85	1.05
B	1.50	1.70	a	0.35	0.50
C	0.90	1.30	c	0.10	0.20
L1	2.60	3.00	b	0.35	0.55
E	1.80	2.00	F	0	0.15

SOT23-6

印章说明 / Marking Instructions



说明：

3411： 为型号代码

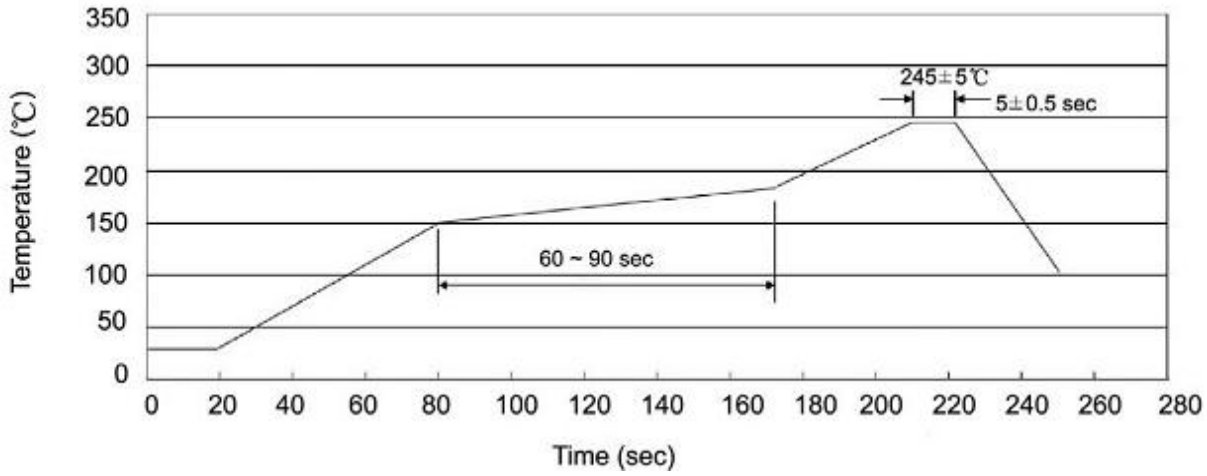
****： 为生产批号代码，随生产批号变化。

Note:

3411: Product Type.

****: Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

1、预热温度 150～180℃，时间 60～90sec;

2、峰值温度 245±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:150~180℃, Time:60~90sec.

2.Peak Temp.:245±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp:260±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT23-5/6	3,000	10	30,000	4	120,000	7″ ×8	210×205×205	445×230×435

使用说明 / Notices